SW Test Workshop
Semiconductor Wafer Test Workshop

Verification of Singulated HBM2 stacks with a KGS Test Cell

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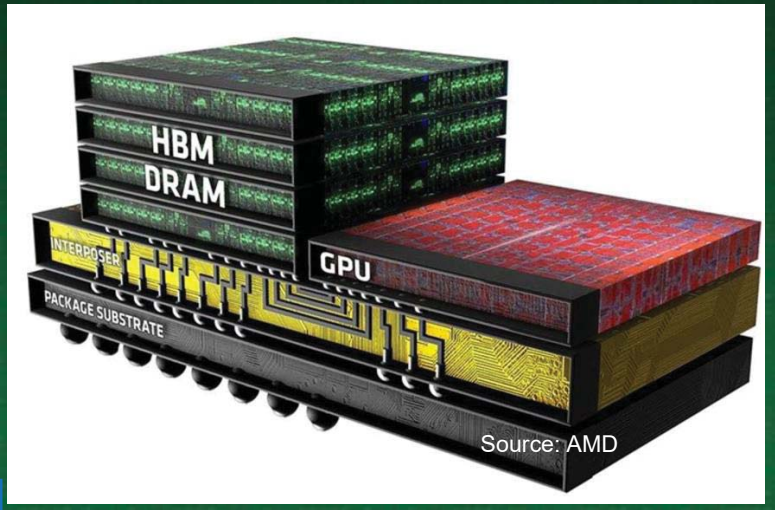
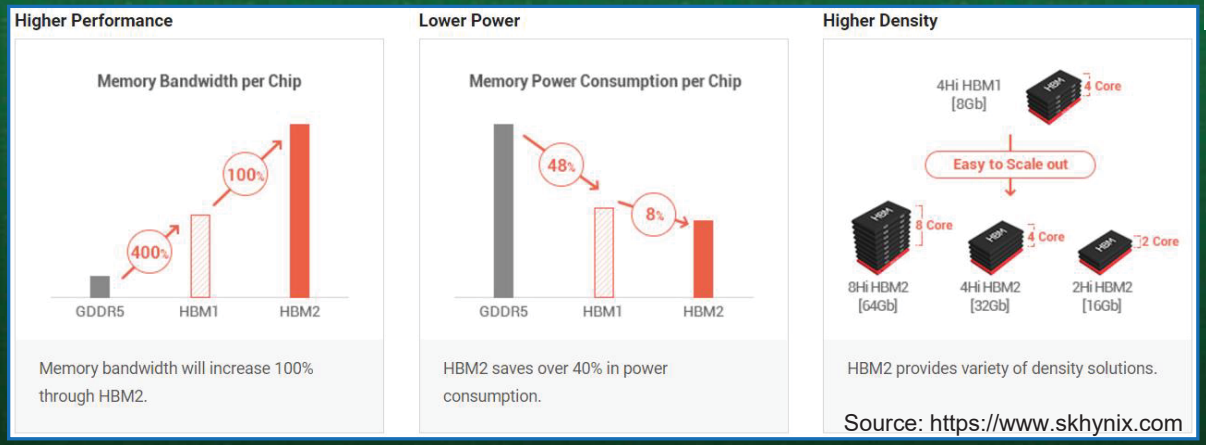
Paper Discussion Outline

- **Industry Need for High Performance HBM Memory**
  - Performance benefits and application drivers
  - HBM process flow and critical test insertion point
  - Known good stack die probing key challenges
- **Probe card design challenges: probing on micro-bump at <60um pitch**
  - Design rules for high speed
  - Space Transformation technology development
- **Direct on Micro-bump probing results**
  - Overdrive versus probe force & probe diameter discussion
  - Ambient scrub mark pictures & result
  - High temperature scrub mark & test result
- **Actual ATE Signal output/input performance on HBM2 device**
  - Simulation vs Actual Measurement result @ 2Gbps
  - 1ch drive vs 8ch simultaneous drive actual result
  - 1.6GHz/3.2Gbps simulation result
- **Proven benefits of this approach & Next Steps**
  - Final product testing
  - High temperature and High frequency

HBM Addresses the Industry's Need for High Performance Memory

- **Increased Bandwidth**
- **Lower Power Consumption**
- **Higher Density Package**
  - HBM provide higher bandwidth than GDDR5 technology
  - 40% less power consumption
  - Smaller form factor with variety of density solutions

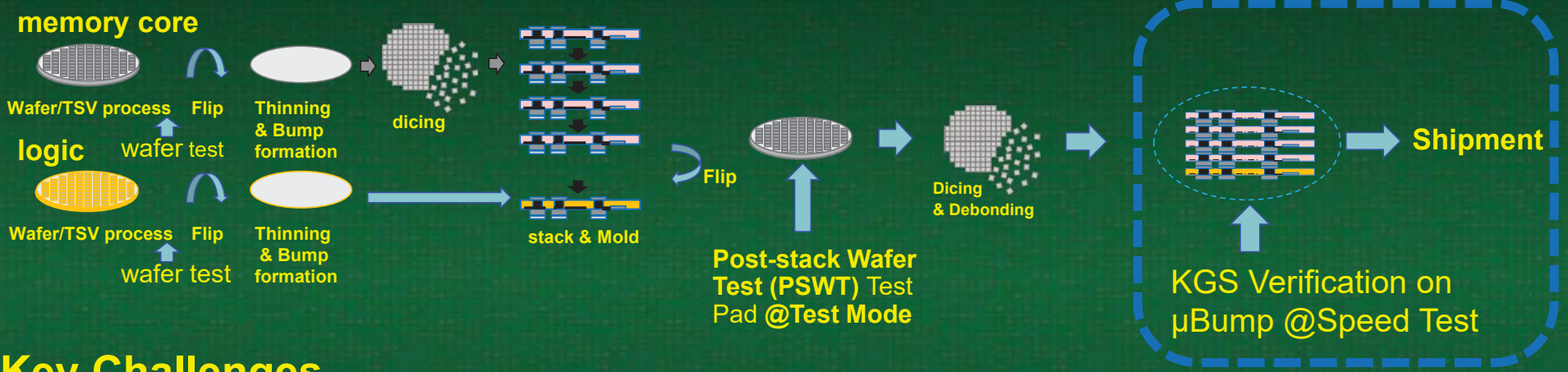




Applications and drivers

- Graphic card
- Server/Network
- Game Console
- High performance computing
- Personal Computer
- Artificial Intelligence

HBM Flow and KGSD Test Challenges



Key Challenges

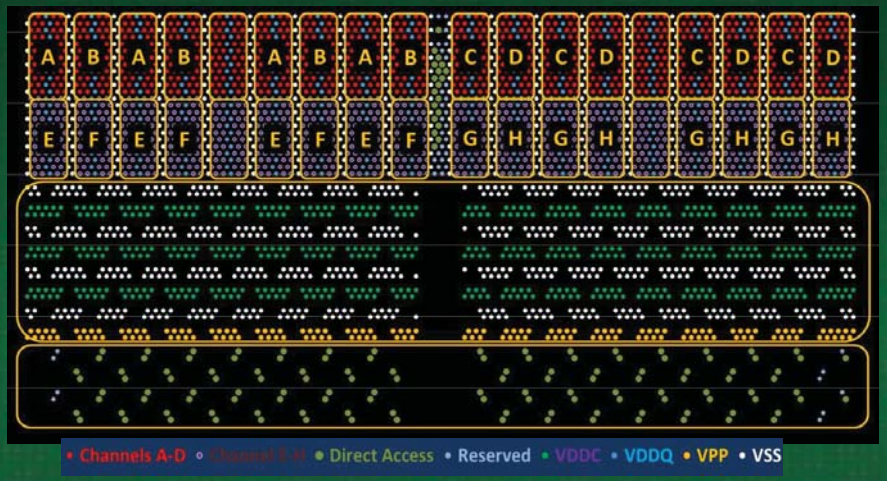
- Handling of bare stack die
- Thermal movement
- Contact stability at elevated temperature
- Micro-bump “coining” behavior at high temp

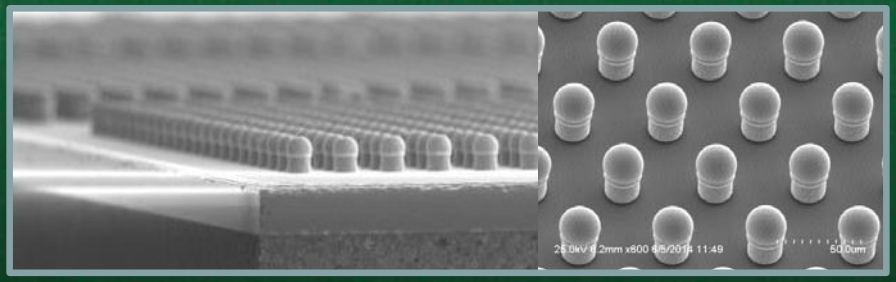
Known-Good-Stack Testing Goals

- Contact all micro-bumps on HBM stacks to allow native mode functional and performance testing on all eight memory channels.
- Support at-speed testing > 2.4Gbps.
- Supports extreme temperature testing.
- Reliable contact to ~4,000 micro-bumps with a pitch of 55um.

Probe Card Design Requirement

JEDEC HBM2 Layout Configuration

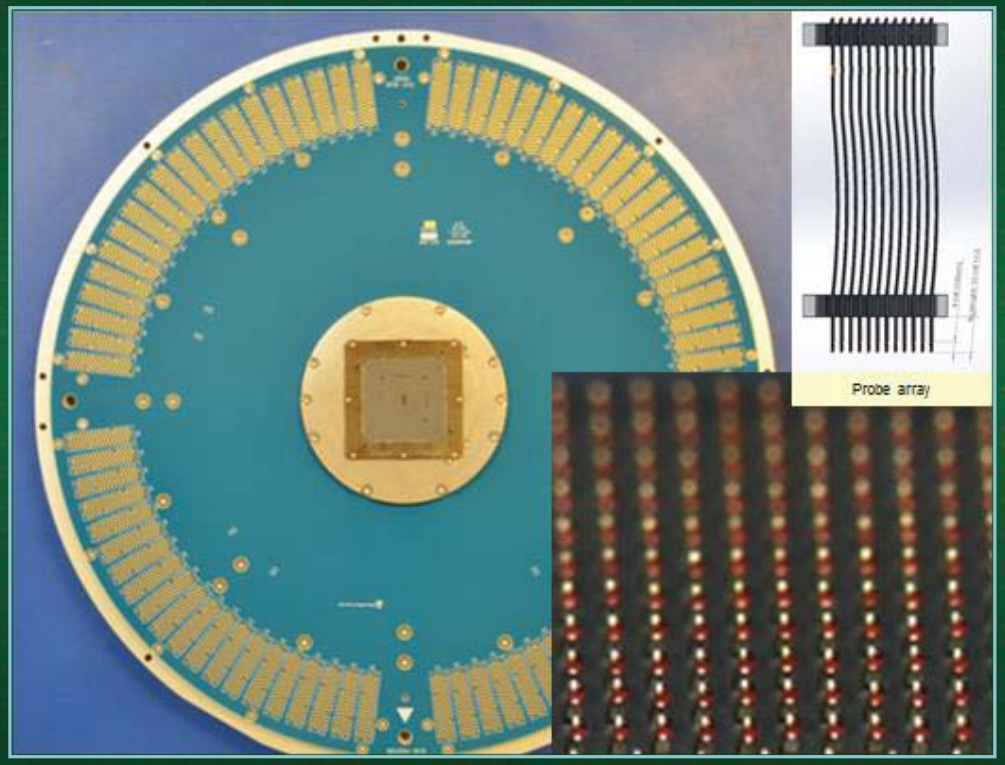




- HBM Array Structure
  - Total TSV Micro Bumps: 3990
    - 55µm Micro Bump Pitch (27.5 x 48um staggered)
  - Total IO Micro Bumps: 1728
  - Direct access micro bumps176
  - Total Power Supplies: 3 – 1056
  - Total ground Micro Bumps: 1030
- **Array size**
  - 6022µm x 2832µm
- **Test requirement**
  - 2.133 Gb/s Functional test of the stack
  - All 8 device channels

Probe card design challenges

Probing on TSV bump at 55um pitch



Actual FFI Apollo MF40 Probe Card

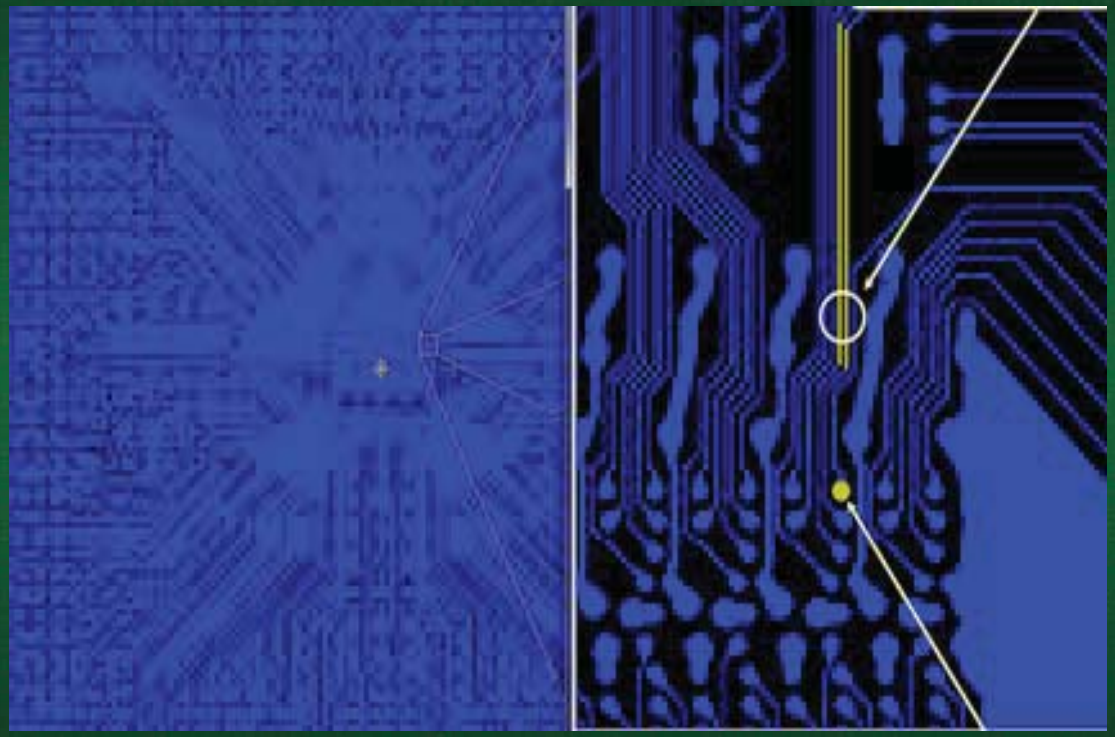
FormFactor Solution

- **Apollo MF40 MEMs**
  - High speed grid array application
  - 2Gbps on TSV Micro-bump

Challenges:

- Design rules for high speed
  - SI simulation validation
  - Impedance control from LIF to Tip
- ST Trace geometry
  - Line & Space technology
  - Routing challenges
- ST Manufacturability

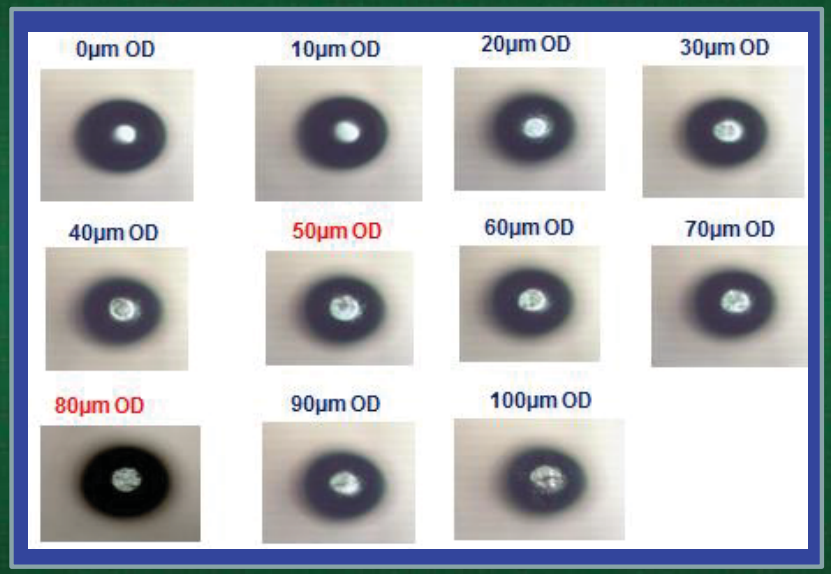
Space Transformation Design Challenges

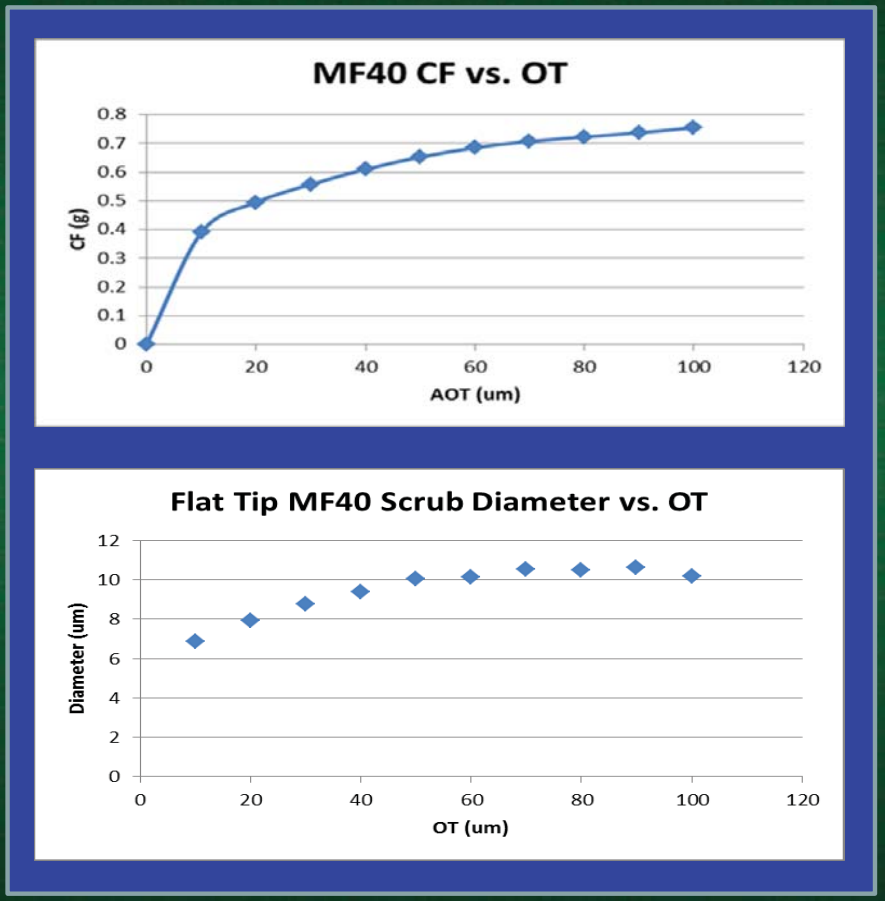


Small die size, high bump counts

- **~4000 traces in ~6x3mm**
- **FFI proprietary ST MLO fan-out design enabler**
  - Pushing the MLO technology limit
  - Co-develop additional capability for high speed requirement
  - Line/space and layer count
- **Impedance control optimization**
  - Minimize voltage reflection & cross talk

FFI MF40 Micro-Bump Probing Characteristics



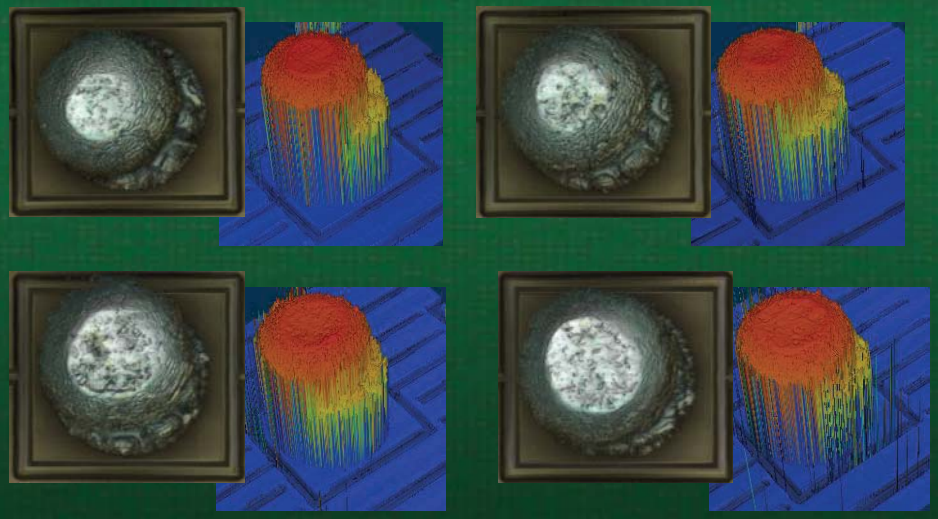


HBM2 Die Micro-bump Probing Results - Ambient

- **We succeeded in contacting all I/O pins**
- **Ambient scrub mark pictures & result**
  - Contact Time:6sec, Contact : 1 time vs 2 times
  - Contact Time:600sec, Contact : 1 time vs 2 times

The scrub becomes deeper as the number of contacts increases

The scrub becomes deeper as the test time becomes longer



uBump Diameter : 25um
Over Drive : 60um
Temperature : Ambient

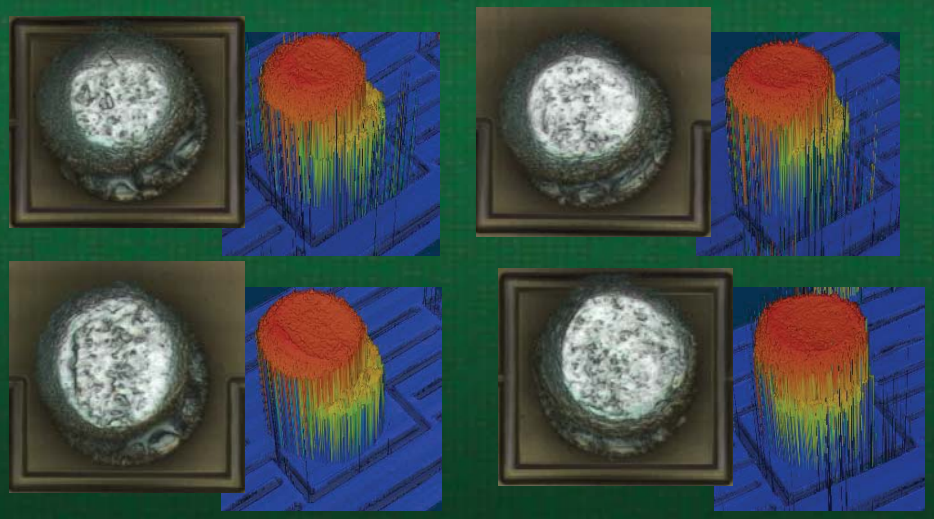
Condition	T.T:6sec 1 time	T.T:6sec 2 times
Scrub depth[um]	0.87	1.72
Scrub diameter[um]	10.86	10.86

Condition	T.T:600sec 1 time	T.T:600sec 2 times
Scrub depth[um]	2.61	2.99
Scrub diameter[um]	14.81	15.04

HBM2 Die Micro-bump Probing Results – High Temperature

- **We succeeded in contacting all I/O pins**
- **High temperature scrub mark & test result**
  - Contact Time:6sec, Contact : 1 time vs 2 times
  - Contact Time:600sec, Contact : 1 time vs 2 times

The scrub becomes deeper as the temperature becomes higher



uBump Diameter : 25um
Over Drive : 60um
Temperature : 105degC

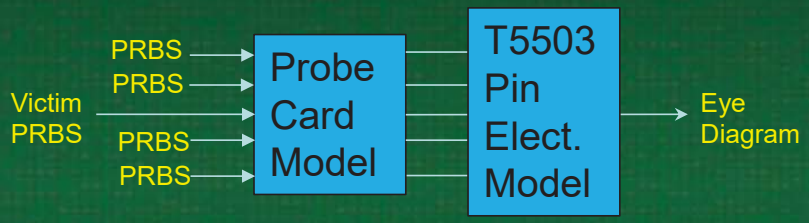
Condition	T.T:6sec 1 time	T.T:6sec 2 times
Scrub depth[um]	1.66	1.84
Scrub diameter[um]	14.34	16.07

Condition	T.T:600sec 1 time	T.T:600sec 2 times
Scrub depth[um]	2.80	3.86
Scrub diameter[um]	17.06	18.71

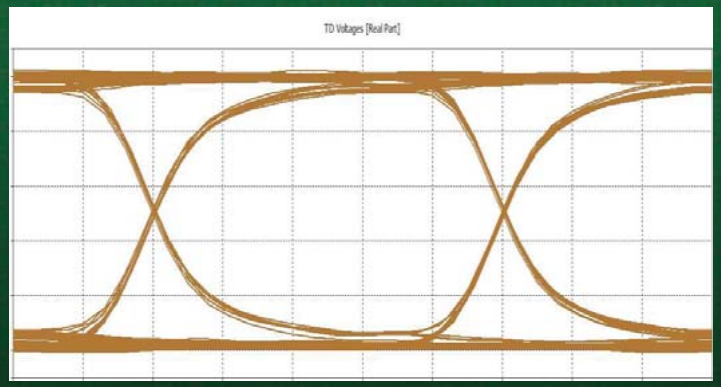
Signal Output/Input Performance on HBM2 Die

- **Simulation vs Actual Measurement result @ 2Gbps**
  - The waveform is similar in simulation and actual measurement on HBM2 die
  - Strong eye-diagram performance correlation

Simulation

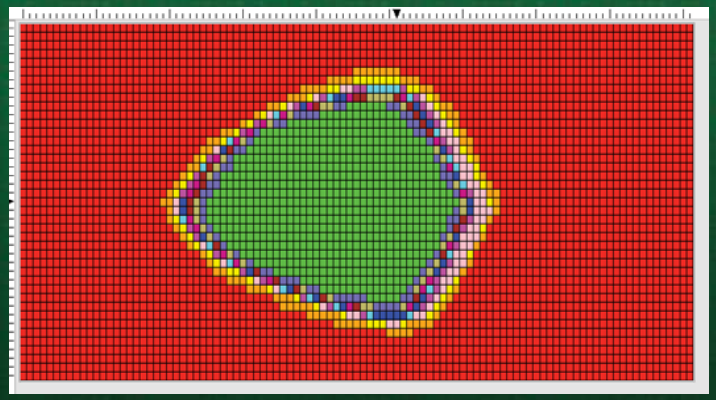


Simulation schematic of HBM as driver at 1 victim



Actual Measurement

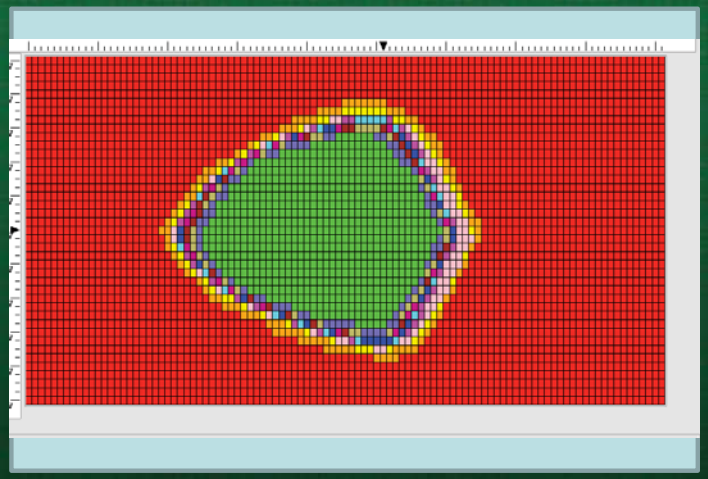
- PRBS signal driver and T5503HS's comparator were terminated with 50Ω.



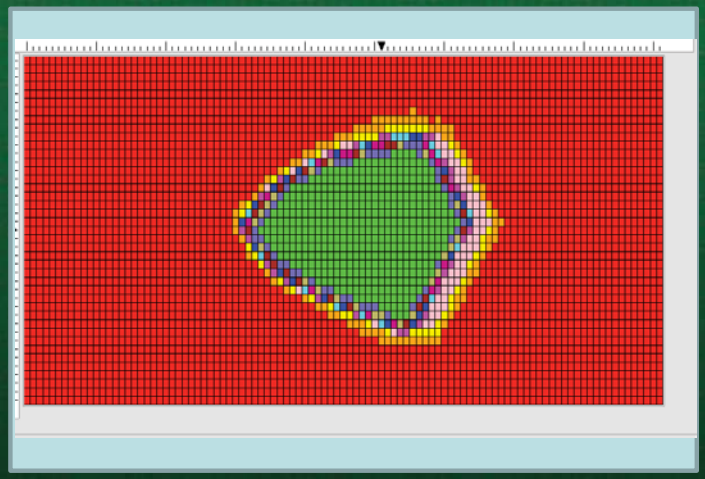
Signal Output/Input Performance on HBM2 Die

- **1ch drive vs 8ch simultaneous drive actual result @ 2Gbps**
  - With data activity on just one memory channel the output data eye width is quite large.
  - With data activity on all eight memory channels the output data eye shrinks.

Shmoo(Dout) 1ch meas. / 1ch drive

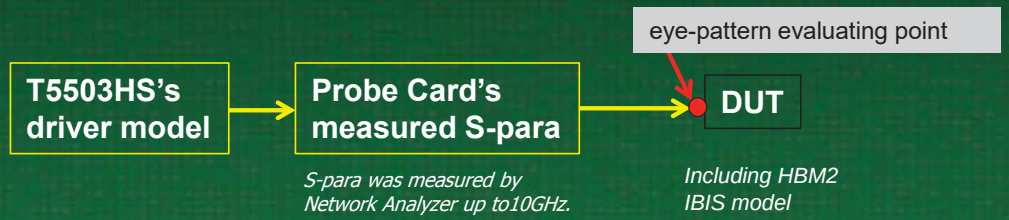


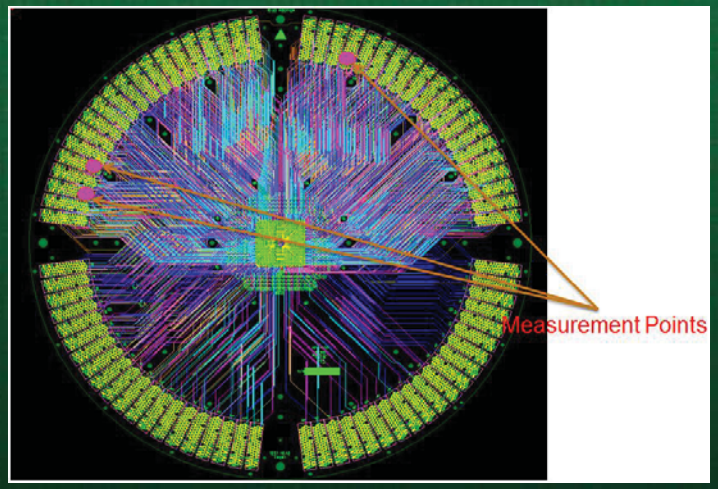
Shmoo(Dout) 1ch meas. / 8ch drives



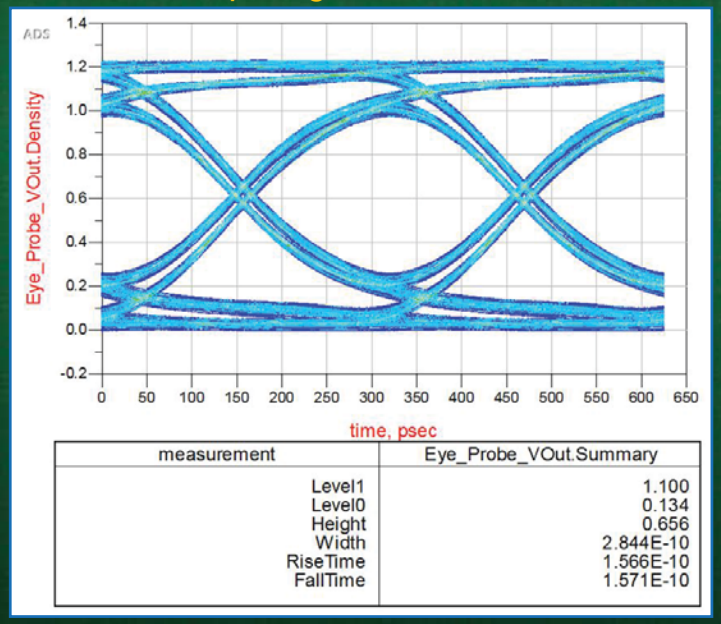
Signal Output/Input at Higher Frequency

- **1.6GHz/3.2Gbps simulation result**
  - MF40 technology supports operating speed to 3.2Gb/s with additional design rules optimization
  - Strong simulation versus actual measurement result as validated through ATE at 2Gbps





3.2Gbps Signal Performance



measurement	Eye_Probe_VOut.Summary
Level1	1.100
Level0	0.134
Height	0.656
Width	2.844E-10
RiseTime	1.566E-10
FallTime	1.571E-10

Benefit Summary

- Working together as a team Advantest together with FormFactor developed a production worthy tool for confirming Known-Good Memory Stacks with ~4,000 micro-bumps and < 60um bump pitch.
- The resulting design exceeded our design goals for probe force and CCC with a wide operational temperature range.
- The solution exceeded our high frequency goal demonstrating >3 Gbps performance.
- The solution contacts to all eight HBM channels simultaneously enabling native mode performance and functional testing of these complex devices.

Acknowledgement

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